

APPLICANTS: Choi et al.  
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### **AMENDMENTS TO THE SPECIFICATION**

Please amend the first paragraph on page 8 of the specification as follows:

The preferred materials and processes for forming the top layer are the same as those for forming the insulating layer, except of course that the conditions used to deposit the top layer should be varied so as to give the top layer substantial conductivity. As is well known to those skilled in the art, the resistance of layers used in electrode assemblies is normally measured over the whole surface of the assembly, and in the present case it has been found that using a top layer with a conductivity of ~~at least~~ less than ~~about~~ 400 ohms/square, and desirably from about 100 to about 200 ohms per square, gives satisfactory results. The thickness of the top layer is desirably in the range of about 20 to about 100 nm.